

REMARKS

The claims as now presented are directed to the subject matter of previous claim 44. For this reason, claim 44, as well as its immediate parent claim 10, have been canceled and their limitations have been incorporated into claim 1.

Claim Rejections - 35 USC § 112

In the previous claim 44, Applicant used the term "useful". This term has been rejected by the Examiner as not complying with 35 USC § 112 second paragraph. In response, Applicant has now presented in claim 1 the same concept, but has clearly claimed structure which is not used. Applicant states in the last three lines "the connections used for known good dye tests are not connected to the end use device." A non-connection means precisely that, and this is a clear, distinct structural limitation. Applicant's specification at the bottom of page 18 and the top of page 19 describes the unusable situation for solder ball connections. Applicant's originally filed claim 29 recites removal of metallic connections from the wire bond pads after testing the dye. Therefore, the specification clearly supports in both instances, no connections. Applicant's specification, pages 8 - 12, also make it very clear that when one set of connections is used, it is used only for a known good dye test and that these same contacts are not used in the context of a multi-chip module (MCM).

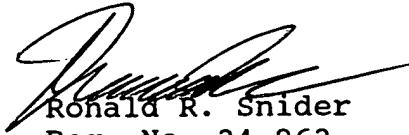
Claim Rejections - 35 USC § 102

The Examiner has rejected claim 1, 3 - 6, 10 and 44 as being anticipated by JP '281. the Examiner has based this rejection on the statement found at the last paragraph of page 2 which is that for purposes of examination an encapsulation connection is considered as being no longer "useful". In claim 1 as now amended, Applicant has described a structure where there is no connection. Here the Examiner should note that a solder bump, or wire bond pad is simply not a connection. It can be thought of as half a connection. Connection is not established until the wire bond pad has a wire on it or the solder bump has a soldered connection to an end use device as now claimed.

In view of the foregoing, it is respectfully submitted that the application is now in condition for allowance, and early action in accordance thereof is requested. In the event there is any reason why the application cannot be allowed in this current

condition, it is respectfully requested that the Examiner contact the undersigned at the number listed below to resolve any problems by Interview or Examiner's Amendment.

Respectfully submitted,



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